

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZEYU XU	07/24/2020
XIONGWEN DENG	07/24/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	BEIJING XIAOMI PINECONE ELECTRONICS CO., LTD.
<b>Street Address:</b>	UNIT C, BUILDING C, NO. 66, ZHUFANG ROAD
<b>Internal Address:</b>	QINGHE STREET, HAIDIAN DISTRICT
<b>City:</b>	BEIJING
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	100085
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16942087
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(202)408-4400
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	202-408-4000
<b>Email:</b>	regional-desk@finnegan.com
<b>Correspondent Name:</b>	FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER
<b>Address Line 1:</b>	901 NEW YORK AVENUE, NW
<b>Address Line 4:</b>	WASHINGTON, D.C. 20001-4413
<b>ATTORNEY DOCKET NUMBER:</b>	13269.0105-00000
<b>NAME OF SUBMITTER:</b>	DEBORAH A. EDDINS
<b>SIGNATURE:</b>	/Deborah A. Eddins/
<b>DATE SIGNED:</b>	07/29/2020
<b>Total Attachments: 3</b>	
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## ASSIGNMENT AND DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION

### ASSIGNMENT:

WHEREAS I/We, the below named inventor(s), (hereinafter referred to as Assignor(s)), of a claimed invention in an application for United States Letters Patent entitled:

#### METHOD FOR PROCESSING INFORMATION, AND STORAGE MEDIUM

filed herewith; and

WHEREAS, Beijing Xiaomi Pinecone Electronics Co., Ltd.  
a corporation of China

whose post office address is Unit C, Building C, No. 66, Zhufang Road, Qinghe Street,  
Haidian District, Beijing, 100085 China

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Director of the United States Patent and Trademark Office to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request that the attorneys having Power of Attorney in this application, insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

### DECLARATION OF INVENTOR(S)

As a named inventor below, I hereby declare that: (1) This declaration is directed to the above-identified application; (2) the above-identified application was made or authorized to be made by me; (3) my residence and mailing address are as stated below next to my name; and (4) I believe I am an original inventor or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statements made in this declaration are punishable by fine or imprisonment of not more than five (5) years, or both, under section 1001 of Title 18 of the United States Code.

As a below named inventor, I have reviewed and understand the contents of the application, including the claims, and am aware of the duty to disclose to the USPTO all information known to me to be material to patentability as defined in 37C.F.R. § 1.56.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

1. FULL NAME OF FIRST ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
XU, Zeyu	XU, Zeyu	7/24/2020
MAILING ADDRESS c/o Beijing Xiaomi Pinecone Electronics Co., Ltd., Unit C, Building C, No. 66, Zhufang Road, Qinghe Street, Haidian District, Beijing, 100085 China		RESIDENCE Beijing, China
2. FULL NAME OF SECOND ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
DENG, Xiongwen		
MAILING ADDRESS c/o Beijing Xiaomi Pinecone Electronics Co., Ltd., Unit C, Building C, No. 66, Zhufang Road, Qinghe Street, Haidian District, Beijing, 100085 China		RESIDENCE Beijing, China

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2. FULL NAME OF SECOND ASSIGNOR	ASSIGNOR'S SIGNATURE	DATE
DENG, Xiongwen	<i>Deng, Xiongwen</i>	7/24/2020
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